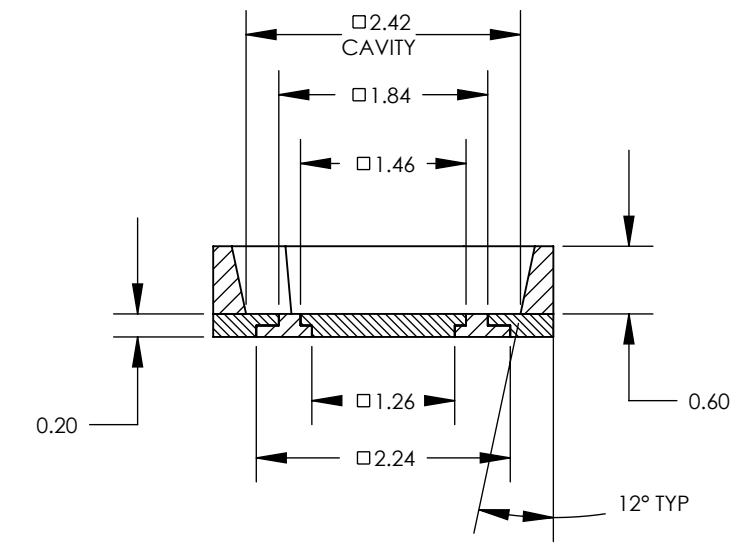
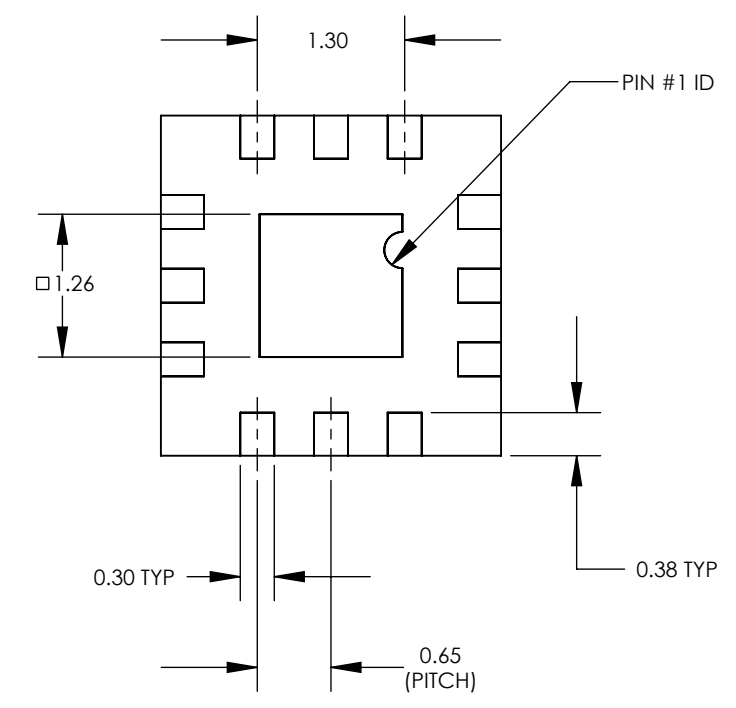
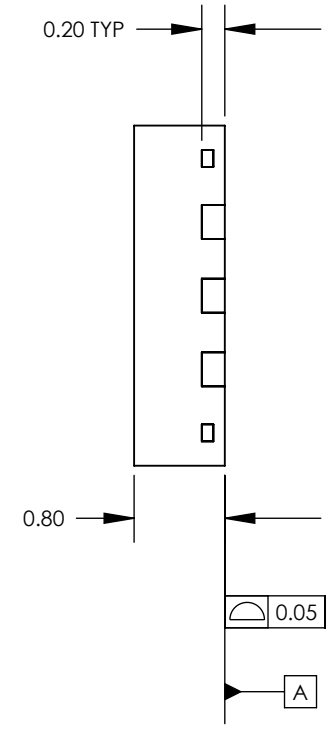
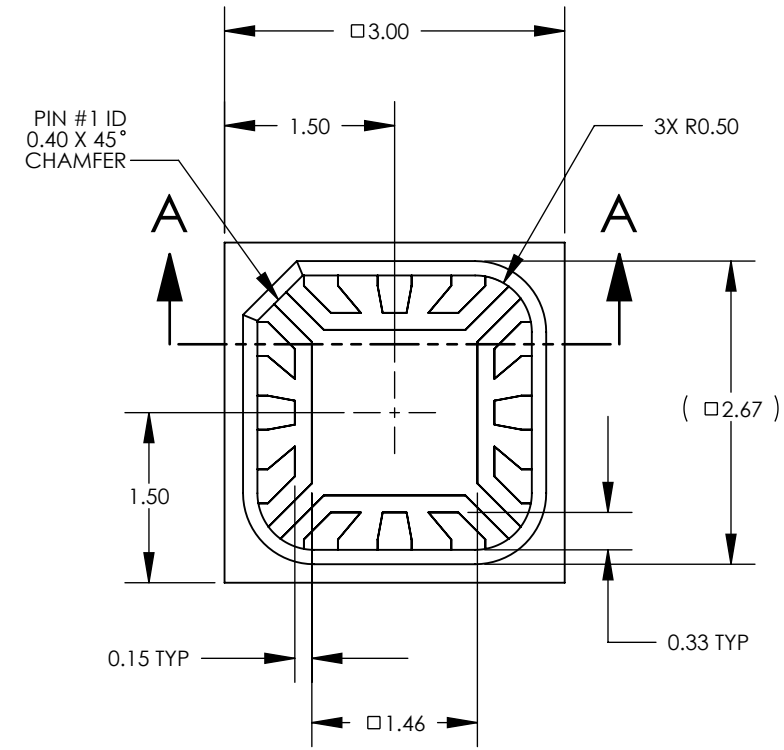


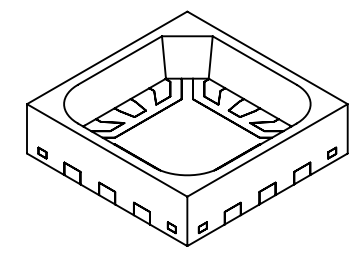
REVISIONS					
ZONE	REV.	DESCRIPTION	DATE	APPROVED	DCN NO.
	A	ORIGINAL RELEASE	8/12/11		




SECTION A-A
SCALE 15:1

NOTES

- MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.
- FINISH:
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICRONS (2.5um-7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um-2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
- PACKAGE CONFORMS TO JEDEC MO-220



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UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .X = ±0.10 .XX: ±0.05		DRAWN	D. Abbe	8/12/11	 QPTECHNOLOGIES <small>A DIVISION OF PROMEX INDUSTRIES QPTECHNOLOGIES.COM</small>
		CHECKED	S. Swen	8/12/11	
		ENG APPR.	S. Swen	8/12/11	
		COMMENTS:			TITLE: QP-QFN12-3MM-0.65MM
MATERIAL	SEE NOTE 1	SIZE	DWG. NO.	REV	
FINISH	SEE NOTE 2	B	500415	A	
NEXT ASSY	USED ON	SCALE: 16:1	WEIGHT:	SHEET 1 OF 1	
APPLICATION	DO NOT SCALE DRAWING				

